

HIGH-SPEED COMPRESSION INTERPOSER

(0.80 mm) .0315" AND (1.00 mm) .0394" PITCH

FEATURES & BENEFITS

- Dual compression contacts or single compression with solder balls
- BeCu Micro-formed contacts
- Performance up to 14 Gbps (ZAX Series)
- Low-profile body height for a short signal path
- Highly customizable solutions
- Visit samtec.com?ZRDP for ultra-low profile Z-Ray® cable assembly



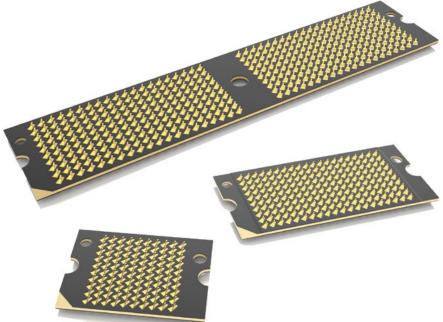
Solder Ball Option

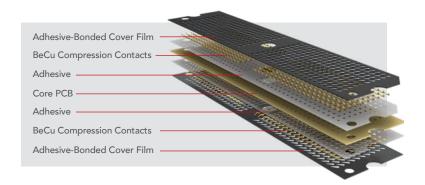


BeCu Compression Contacts

Design & Construction

- One-piece design assembled into rugged low profile FR4 substrate under high pressure and temperature
- Built standard with a 1 mm board-to-board thickness
- Contacts are designed using BeCu foils that have been formed into the "beam" structure





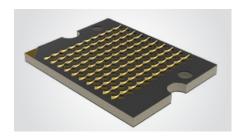
PERFORMANCE SPECIFICATIONS						
	Single Compression w/ Solder Balls			Dual Compression		
Series		ZA8	ZA1	ZA8	ZA1	
Pitch		0.80 mm	1.00 mm	0.80 mm	1.00 mm	
Max Row		25	20	50	58	
Max Column		25	20	50	58	
Thickness	FR4 Core	1.00 to 3 mm	1.00 to 3 mm	0.5 to 3 mm	0.5 to 3 mm	
Thickness Tolerance	FR4 Core	±10%	±10%	±10%	±10%	
Deflection / Normal Force per Pin		0.20 mm / 30g				
Operating Temperature		-55°C to +105°C (Single Cycle only above 85°C)				

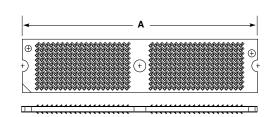




(1.00 mm) .0394" PITCH • HIGH-SPEED COMPRESSION INTERPOSER

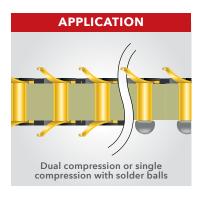


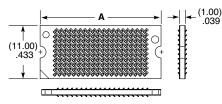


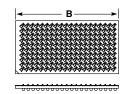


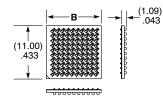
40 X 10 DUAL COMPRESSION

POSITIONS PER ROW	A	В	
-10	(14.30) .563	(11.40) .449	
-20	(24.30) .957	(21.40) .843	
-30	(38.30) 1.508	N/A	
-40	(48.30) 1.902	N/A	









20 X 10 DUAL COMPRESSION

20 X 10 COMPRESSION WITH SOLDER BALLS

10 X 10 COMPRESSION WITH SOLDER BALLS

View complete specifications at: samtec.com?ZA1

Ultimate Design Flexibility

- Configurations for any application, complete with detailed footprints
- Customer-specific stack heights, pin counts, insulator shapes and plating thicknesses
- Customizable in X-Y-Z axes
- Quick-turn customization with minimal NRE and tooling charges
- Various compression and alignment configurations

